

MB6F THRU MB10F
BRIDGE RECTIFIERS



VOLTAGE: 600~1000 Volts	CURRENT: 1.0 Amperes	MBF	Marking & Schematic diagram
FEATURES		<p>Remark:</p> <ol style="list-style-type: none"> ①. NH=niuhang trademark ②. FF=Product line code,According to actual changes YWW=Data code,According to actual changes ③. MBxxF=Modle,xx=6,8,10 ④. "- "+"=Polarity mark 	
MECHANICAL DATA			
TYPICAL APPLICATIONS			

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Maximum Ratings (Ratings at 25°C ambient temperature unless otherwise specified)

Parameter	Symbol	MB6F	MB8F	MB10F	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	600	800	1000	V
Maximum Average Forward Rectified Current @ TC=100°C (see fig.1)	$I_{F(AV)}$	1.0			A
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed On Rate Load (JEDEC Method)	I_{FSM}	30			A
Current Squared Time Per Diode(t<8.3ms)	I^2t	3.74			A ² sec

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified)

Parameter	Test Conditions	Symbol	MB6F	MB8F	MB10F	Unit
Maximum Forward Voltage Per Diode (Note 1)	Ta=25°C IF= 1.0 A	V_{FM}	1.1			V
Maximum DC Reverse Current at Rated DC Blocking Voltage (Note 1)	Ta=25°C @ VR V	I_{RRM}	5			uA
	Ta=125°C @ VR V		300			
Typical Junction Capacitance Per Diode	4V,1MHz	C_J	13			pF

Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified)

Parameter	Symbol	MB6F	MB8F	MB10F	Unit
Operating Junction Temperature Range	T_J	-55 to +150			°C
Storage Temperature Range	T_{STD}	-55 to +150			
Typical thermal resistance (Note 2)	$R_{\theta JA}$	85			°C/W
	$R_{\theta JC}$	25			

- Notes: 1. Pulse test: 300 μs pulse width, 1% duty cycle
 2. Device mounted on Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

MB6F THRU MB10F
BRIDGE RECTIFIERS



RATING AND CHARACTERISTIC CURVES

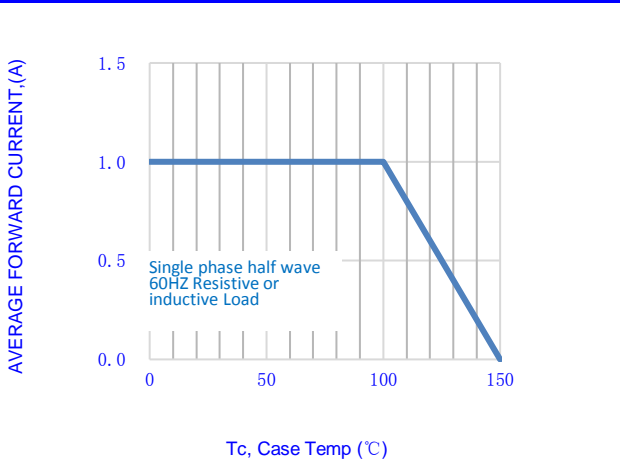


Fig.1-FORWARD CURRENT DERATING CURVE

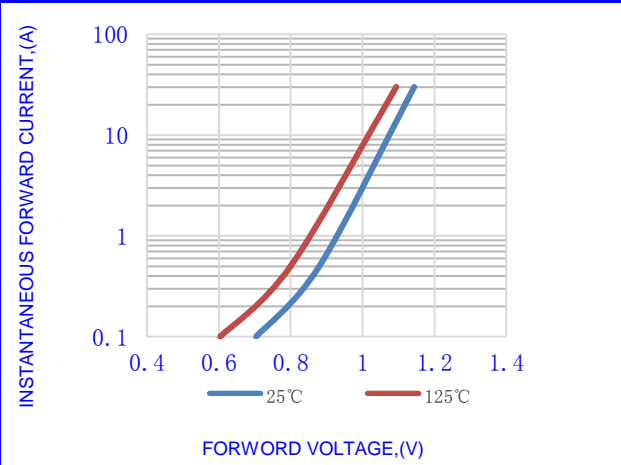


Fig.2- TYPICAL INSTANTANEOUS FORWARD

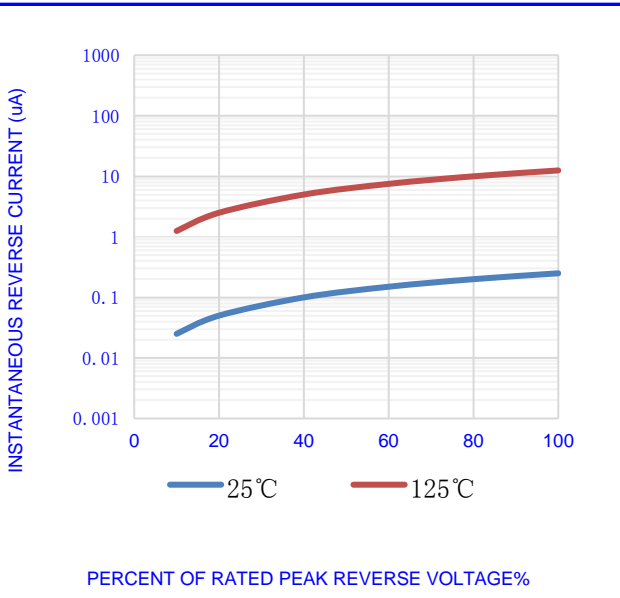


Fig.3- TYPICAL REVERSE CHARACTERISTICS

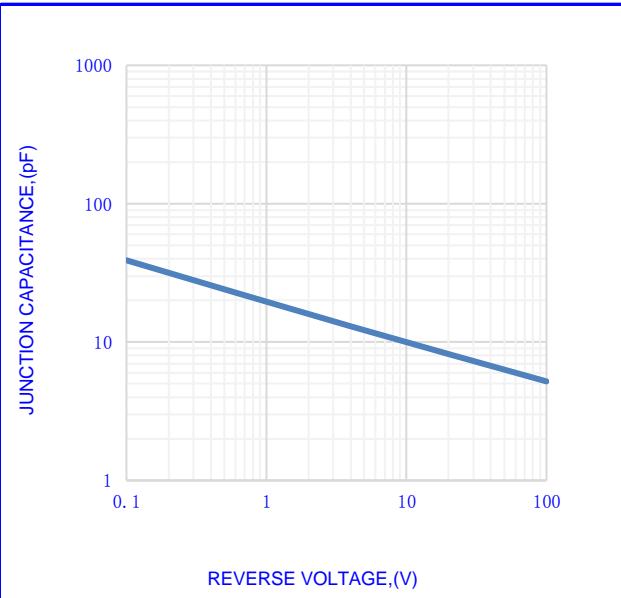


Fig.4- TYPICAL JUNCTION CAPACITANCE

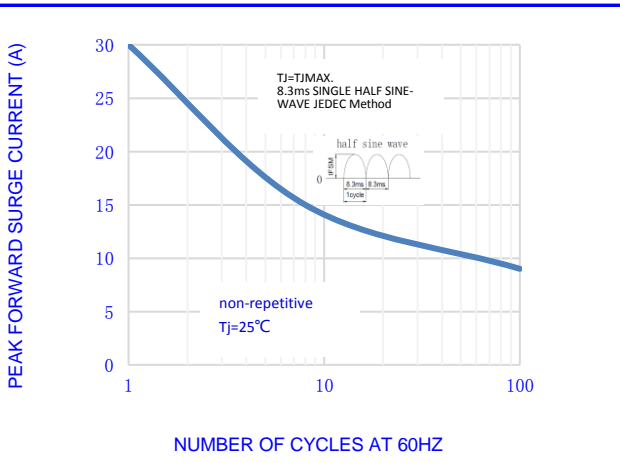


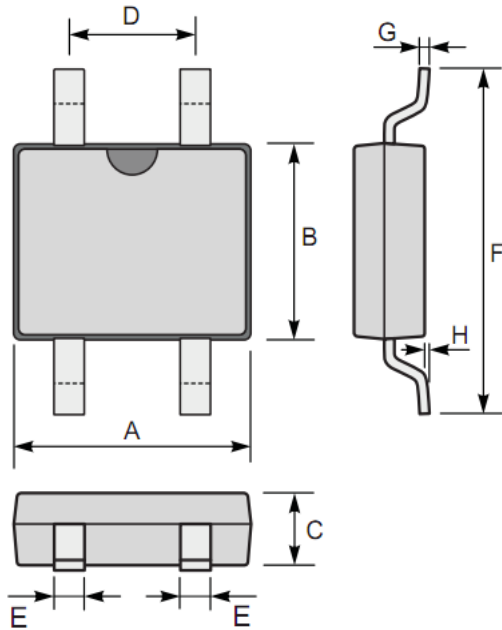
Fig.5-MAX. NON-REPETITIVE SURGE CURRENT

MB6F THRU MB10F
BRIDGE RECTIFIERS



OUTLINE DRAWINGS

MBF

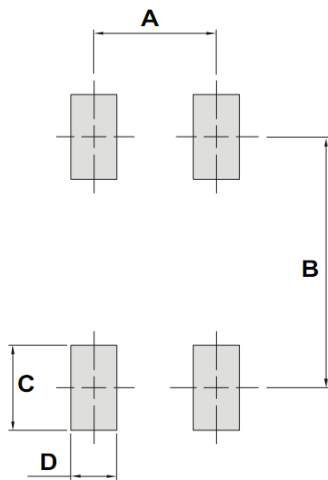


OUTLINE DIMENSIONS

Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.500	-	4.900	0.177	-	0.193
B	3.600	-	4.000	0.142	-	0.157
C	1.200	-	1.600	0.047	-	0.063
D	2.200	-	2.800	0.087	-	0.110
E	0.450	-	1.050	0.018	-	0.041
F	6.600	-	7.000	0.260	-	0.276
G	0.150	-	0.350	0.006	-	0.014
H	-	-	0.200	-	-	0.008

RECOMMENDED LAYOUT DRAWINGS

MBF



RECOMMENDED LAYOUT DIMENSIONS

Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	2.400	-	-	0.0945	-
B	-	6.000	-	-	0.2362	-
C	-	1.840	-	-	0.0724	-
D	-	0.900	-	-	0.0354	-

PACKING INFORMATION

MBF

Package Method	Reel Size (mm)	Quantity (pcs/reel)	Inner Box Size LxWxH(mm)	Quantity (pcs/Inner Box)	Outer Carton Size LxWxH(mm)	Quantity (pcs/carton)
Tape Reel	Φ330	5000	340x340x40	10000	360x360x260	60000

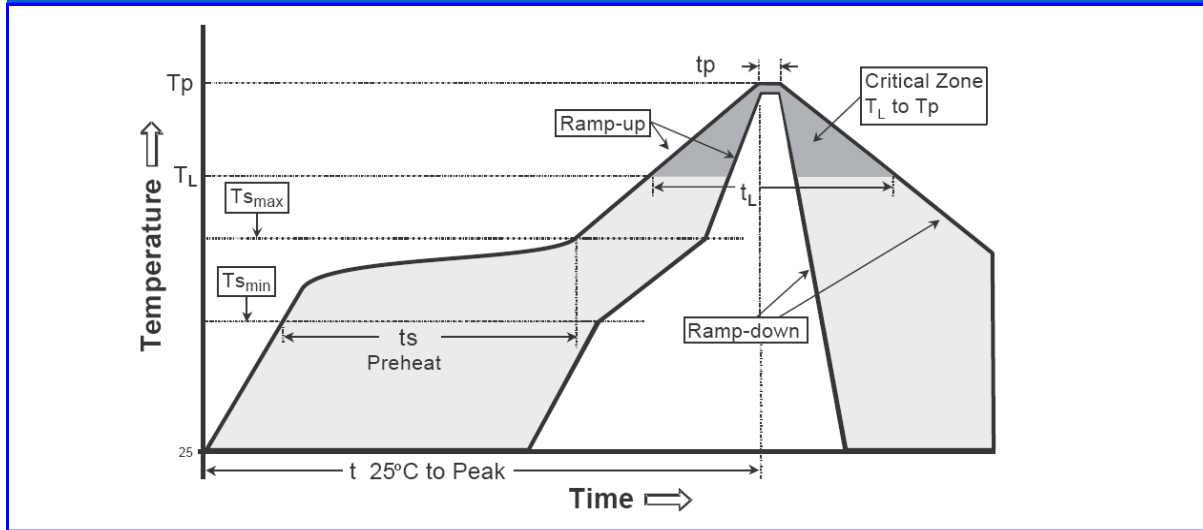
MB6F THRU MB10F
BRIDGE RECTIFIERS



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmmax to Tp)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(TS min) -Temperature Max(TS max) -Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (TL) - Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

MB6F THRU MB10F
BRIDGE RECTIFIERS



Disclaimer

- Reproducing and modifying information of the document is prohibited without permission from niuhang Electronics co., LTD
- Niuhan Electronics co., LTD. reserves the rights to make changes of the content herein the document anytime without notification.
- Niuhan Electronics co., LTD. disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially occurred.
- Niuhan Electronics co., LTD. does not assume any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.
- Applications shown on the herein document are examples of standard use and operation. Customers are responsible in comprehending the suitable use in particular applications. Niuhan Electronics co., LTD. makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.
- The products shown herein are not designed and authorized for equipments requiring high level of reliability or relating to human life and for any applications concerning life-saving or life-sustaining, such as medical instruments, transportation equipment, aerospace machinery et cetera. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Niuhan Electronics co., LTD. for any damages resulting from such improper use or sale.
- When the appearance of the product and chip size does not change, in order to product the customer quality, change the internal structure and the production process Niuhan can not notify